Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, Cap Sense, DMA, I²S, POR, PWM, WDT
Number of I/O	51
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 20x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l151r6t6tr

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Table 5. Working mode-dependent functionalities (from Run/active down to standby)

Ips	Run/Active	Sleep	Low-power Run	Low-power Sleep	Stop		Standby	
						Wakeup capability		Wakeup capability
CPU	Y	-	Y	-	-	-	-	-
Flash	Y	Y	Y	Y	-	-	-	-
RAM	Y	Y	Y	Y	Y	-	-	-
Backup Registers	Y	Y	Y	Y	Y	-	Y	-
EEPROM	Y	-	Y	Y	Y	-	-	-
Brown-out rest (BOR)	Y	Y	Y	Y	Y	Y	Y	-
DMA	Y	Y	Y	Y	-	-	-	-
Programmable Voltage Detector (PVD)	Y	Y	Y	Y	Y	Y	Y	-
Power On Reset (POR)	Y	Y	Y	Y	Y	Y	Y	-
Power Down Rest (PDR)	Y	Y	Y	Y	Y	-	Y	-
High Speed Internal (HSI)	Y	Y	-	-	-	-	-	-
High Speed External (HSE)	Y	Y	-	-	-	-	-	-
Low Speed Internal (LSI)	Y	Y	Y	Y	Y	-	Y	-
Low Speed External (LSE)	Y	Y	Y	Y	Y	-	Y	-
Multi-Speed Internal (MSI)	Y	Y	Y	Y	-	-	-	-
Inter-Connect Controller	Y	Y	Y	Y	-	-	-	-
RTC	Y	Y	Y	Y	Y	Y	Y	-
RTC Tamper	Y	Y	Y	Y	Y	Y	Y	Y
Auto Wakeup (AWU)	Y	Y	Y	Y	Y	Y	Y	Y
LCD	Y	Y	Y	Y	Y	-	-	-
USB	Y	Y	-	-	-	Y	-	-
USART	Y	Y	Y	Y	Y	(1)	-	-
SPI	Y	Y	Y	Y	-	-	-	-
I2C	Y	Y	Y	Y	-	(1)	-	-
ADC	Y	Y	-	-	-	-	-	-

3.15.5 Window watchdog (WWDG)

The window watchdog is based on a 7-bit down-counter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early warning interrupt capability and the counter can be frozen in debug mode.

3.16 Communication interfaces

3.16.1 I²C bus

Up to two I²C bus interfaces can operate in multimaster and slave modes. They can support standard and fast modes.

They support dual slave addressing (7-bit only) and both 7- and 10-bit addressing in master mode. A hardware CRC generation/verification is embedded.

They can be served by DMA and they support SM Bus 2.0/PM Bus.

3.16.2 Universal synchronous/asynchronous receiver transmitter (USART)

All USART interfaces are able to communicate at speeds of up to 4 Mbit/s. They provide hardware management of the CTS and RTS signals and are ISO 7816 compliant. They support IrDA SIR ENDEC and have LIN Master/Slave capability.

All USART interfaces can be served by the DMA controller.

3.16.3 Serial peripheral interface (SPI)

Up to two SPIs are able to communicate at up to 16 Mbits/s in slave and master modes in full-duplex and half-duplex communication modes. The 3-bit prescaler gives 8 master mode frequencies and the frame is configurable to 8 bits or 16 bits. The hardware CRC generation/verification supports basic SD Card/MMC modes.

Both SPIs can be served by the DMA controller.

3.16.4 Universal serial bus (USB)

The STM32L151x6/8/B and STM32L152x6/8/B devices embed a USB device peripheral compatible with the USB full speed 12 Mbit/s. The USB interface implements a full speed (12 Mbit/s) function interface. It has software-configurable endpoint setting and supports suspend/resume. The dedicated 48 MHz clock is generated from the internal main PLL (the clock source must use a HSE crystal oscillator).

3.17 CRC (cyclic redundancy check) calculation unit

The CRC (cyclic redundancy check) calculation unit is used to get a CRC code from a 32-bit data word and a fixed generator polynomial.

Among other applications, CRC-based techniques are used to verify data transmission or storage integrity. In the scope of the EN/IEC 60335-1 standard, they offer a means of verifying the Flash memory integrity. The CRC calculation unit helps compute a signature of the software during runtime, to be compared with a reference signature generated at link-time and stored at a given memory location.

3.18 Development support

Serial wire JTAG debug port (SWJ-DP)

The ARM SWJ-DP interface is embedded, and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target. The JTAG JTMS and JTCK pins are shared with SWDAT and SWCLK, respectively, and a specific sequence on the JTMS pin is used to switch between JTAG-DP and SW-DP.

The JTAG port can be permanently disabled with a JTAG fuse.

Embedded Trace Macrocell™

The ARM Embedded Trace Macrocell provides a greater visibility of the instruction and data flow inside the CPU core by streaming compressed data at a very high rate from the STM32L151x6/8/B and STM32L152x6/8/B device through a small number of ETM pins to an external hardware trace port analyzer (TPA) device. The TPA is connected to a host computer using USB, Ethernet, or any other high-speed channel. Real-time instruction and data flow activity can be recorded and then formatted for display on the host computer running debugger software. TPA hardware is commercially available from common development tool vendors. It operates with third party debugger software tools.

Table 8. STM32L151x6/8/B and STM32L152x6/8/B pin definitions

Pins					Pin name	Pin type(1)	I/O structure	Main function(2) (after reset)	Pins functions	
LQFP100	LQFP64	TFBGA64	UFBGA100	LQFP48 or UFQFPN48					Alternate functions	Additional functions
1	-	-	B2	-	PE2	I/O	FT	PE2	TRACECLK/LCD_SEG38/TIM3_ETR	-
2	-	-	A1	-	PE3	I/O	FT	PE3	TRACED0/LCD_SEG39/TIM3_CH1	-
3	-	-	B1	-	PE4	I/O	FT	PE4	TRACED1/TIM3_CH2	-
4	-	-	C2	-	PE5	I/O	FT	PE5	TRACED2/TIM9_CH1	-
5	-	-	D2	-	PE6-WKUP3	I/O	FT	PE6	TRACED3/TIM9_CH2	WKUP3
6	1	B2	E2	1	V_{LCD}(3)	S		V_{LCD}	-	-
7	2	A2	C1	2	PC13-WKUP2	I/O	FT	PC13	-	RTC_TAMP1/RTC_TS/RTC_OUT/WKUP2
8	3	A1	D1	3	PC14-OSC32_IN(4)	I/O	TC	PC14	-	OSC32_IN
9	4	B1	E1	4	PC15-OSC32_OUT(4)	I/O	TC	PC15	-	OSC32_OUT
10	-	-	F2	-	V_{SS_5}	S	-	V_{SS_5}	-	-
11	-	-	G2	-	V_{DD_5}	S	-	V_{DD_5}	-	-
12	5	C1	F1	5	PH0-OSC_IN(5)	I/O	TC	PH0	-	OSC_IN
13	6	D1	G1	6	PH1-OSC_OUT	I/O	TC	PH1	-	OSC_OUT
14	7	E1	H2	7	NRST	I/O	RST	NRST	-	-
15	8	E3	H1	-	PC0	I/O	FT	PC0	LCD_SEG18	ADC_IN10//COMP1_INP
16	9	E2	J2	-	PC1	I/O	FT	PC1	LCD_SEG19	ADC_IN11/COMP1_INP
17	10	F2	J3	-	PC2	I/O	FT	PC2	LCD_SEG20	ADC_IN12/COMP1_INP
18	11	-(6)	K2	-	PC3	I/O	TC	PC3	LCD_SEG21	ADC_IN13/COMP1_INP

Table 9. Alternate function input/output (continued)

Port name	Digital alternate function number														
	AFIO0	AFIO1	AFIO2	AFIO3	AFIO4	AFIO5	AFOI6	AFIO7	AFIO8	AFIO9	AFIO11	AFIO12	AFIO13	AFIO14	AFIO15
	Alternate function														
	SYSTEM	TIM2	TIM3/4	TIM9/10/11	I2C1/2	SPI1/2	N/A	USART1/2/3	N/A	N/A	LCD	N/A	N/A	RI	SYSTEM
PD13	-	-	TIM4_CH2	-	-	-	-	-	-	-	-	-	-	TIMx_IC2	EVENTOUT
PD14	-	-	TIM4_CH3	-	-	-	-	-	-	-	-	-	-	TIMx_IC3	EVENTOUT
PD15	-	-	TIM4_CH4	-	-	-	-	-	-	-	-	-	-	TIMx_IC4	EVENTOUT
PE0	-	-	TIM4_ETR	TIM10_CH1	-	-	-	-	-	-	-	-	-	TIMx_IC1	EVENTOUT
PE1	-	-		TIM11_CH1	-	-	-	-	-	-	-	-	-	TIMx_IC2	EVENTOUT
PE2	TRACECK	-	TIM3_ETR	-	-	-	-	-	-	-	-	-	-	TIMx_IC3	EVENTOUT
PE3	TRACED0	-	TIM3_CH1	-	-	-	-	-	-	-	-	-	-	TIMx_IC4	EVENTOUT
PE4	TRACED1	-	TIM3_CH2	-	-	-	-	-	-	-	-	-	-	TIMx_IC1	EVENTOUT
PE5	TRACED2	-	-	TIM9_CH1*	-	-	-	-	-	-	-	-	-	TIMx_IC2	EVENTOUT
PE6	TRACED3	-	-	TIM9_CH2*	-	-	-	-	-	-	-	-	-	TIMx_IC3	EVENTOUT
PE7	-	-	-	-	-	-	-	-	-	-	-	-	-	TIMx_IC4	EVENTOUT
PE8	-	-	-	-	-	-	-	-	-	-	-	-	-	TIMx_IC1	EVENTOUT
PE9	-	TIM2_CH1_ETR	-	-	-	-	-	-	-	-	-	-	-	TIMx_IC2	EVENTOUT
PE10	-	TIM2_CH2	-	-	-	-	-	-	-	-	-	-	-	TIMx_IC3	EVENTOUT
PE11	-	TIM2_CH3	-	-	-	-	-	-	-	-	-	-	-	TIMx_IC4	EVENTOUT
PE12	-	TIM2_CH4	-	-	-	SPI1_NSS	-	-	-	-	-	-	-	TIMx_IC1	EVENTOUT
PE13	-	-	-	-	-	SPI1_SCK	-	-	-	-	-	-	-	TIMx_IC2	EVENTOUT
PE14	-	-	-	-	-	SPI1_MISO	-	-	-	-	-	-	-	TIMx_IC3	EVENTOUT
PE15	-	-	-	-	-	SPI1_MOSI	-	-	-	-	-	-	-	TIMx_IC4	EVENTOUT
PH0-OSC_IN	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

6.3.4 Supply current characteristics

The current consumption is a function of several parameters and factors such as the operating voltage, ambient temperature, I/O pin loading, device software configuration, operating frequencies, I/O pin switching rate, program location in memory and executed binary code. The current consumption is measured as described in *Figure 14: Current consumption measurement scheme*.
All Run-mode current consumption measurements given in this section are performed with a reduced code that gives a consumption equivalent to Dhrystone 2.1 code.

The current consumption values are derived from the tests performed under ambient temperature T_A=25°C and V_{DD} supply voltage conditions summarized in *Table 13: General operating conditions*, unless otherwise specified. The MCU is placed under the following conditions:

The MCU is placed under the following conditions:

- V_{DD} = 3.6 V
- All I/O pins are configured in analog input mode.
- All peripherals are disabled except when explicitly mentioned
- The Flash memory access time, 64-bit access and prefetch is adjusted depending on f_{HCLK} frequency and voltage range to provide the best CPU performance.
- When the peripherals are enabled $f_{APB1} = f_{APB2} = f_{AHB}$
- When PLL is ON, the PLL inputs are equal to HSI = 16 MHz (if internal clock is used) or HSE = 16 MHz (if HSE bypass mode is used).
- The HSE user clock applied to OSC_IN input follows the characteristics specified in *Table 26: High-speed external user clock characteristics*.

Table 24. Peripheral current consumption[1] (continued)

Peripheral		Typical consumption, V_{DD} = 3.0 V, T_A = 25 °C				Unit
		Range 1, V_{CORE}=1.8 V VOS[1:0] = 01	Range 2, V_{CORE}=1.5 V VOS[1:0] = 10	Range 3, V_{CORE}=1.2 V VOS[1:0] = 11	Low power sleep and run	
AHB	GPIOA	5	4.5	3.5	4	µA/MHz (f_{HCLK})
	GPIOB	5	4.5	3.5	4.5	
	GPIOC	5	4.5	3.5	4.5	
	GPIOD	5	4.5	3.5	4.5	
	GPIOE	5	4.5	3.5	4.5	
	GPIOH	4	4	3	3.5	
	CRC	1	0.5	0.5	0.5	
	FLASH	13	11.5	9	18.5	
	DMA1	12	10	8	10.5	
All enabled		166	138	106	130	
$I_{DD\ (RTC)}$		0.47				µA
$I_{DD\ (LCD)}$		3.1				
$I_{DD\ (ADC)}$[3]		1450				
$I_{DD\ (DAC)}$[4]		340				
$I_{DD\ (COMP1)}$		0.16				
$I_{DD\ (COMP2)}$	Slow mode	2				
	Fast mode	5				
$I_{DD\ (PVD\ /\ BOR)}$[5]		2.6				
$I_{DD\ (IWDG)}$		0.25				

1. Data based on differential I_{DD} measurement between all peripherals OFF an one peripheral with clock enabled, in the following conditions: f_{HCLK} = 32 MHz (Range 1), f_{HCLK} = 16 MHz (Range 2), f_{HCLK} = 4 MHz (Range 3), f_{HCLK} = 64kHz (Low power run/sleep), f_{APB1} = f_{HCLK}, f_{APB2} = f_{HCLK}, default prescaler value for each peripheral. The CPU is in Sleep mode in both cases. No I/O pins toggling.
2. HSI oscillator is OFF for this measure.
3. Data based on a differential I_{DD} measurement between ADC in reset configuration and continuous ADC conversion (HSI consumption not included).
4. Data based on a differential I_{DD} measurement between DAC in reset configuration and continuous DAC conversion of V_{DD}/2. DAC is in buffered mode, output is left floating.
5. Including supply current of internal reference voltage.

Table 28. HSE oscillator characteristics(1)(2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{OSC_IN}	Oscillator frequency	-	1		24	MHz
R_F	Feedback resistor	-		200	-	kΩ
C	Recommended load capacitance versus equivalent serial resistance of the crystal (R_S)(3)	R_S = 30 Ω	-	20	-	pF
I_{HSE}	HSE driving current	V_{DD}= 3.3 V, V_{IN} = V_{SS} with 30 pF load	-	-	3	mA
$I_{DD(HSE)}$	HSE oscillator power consumption	C = 20 pF f_{OSC} = 16 MHz	-	-	2.5 (startup) 0.7 (stabilized)	mA
		C = 10 pF f_{OSC} = 16 MHz	-	-	2.5 (startup) 0.46 (stabilized)	
g_m	Oscillator transconductance	Startup	3.5	-	-	mA /V
$t_{SU(HSE)}$(4)	Startup time	V_{DD} is stabilized	-	1	-	ms

1. Resonator characteristics given by the crystal/ceramic resonator manufacturer.
2. Guaranteed by characterization results.
3. The relatively low value of the RF resistor offers a good protection against issues resulting from use in a humid environment, due to the induced leakage and the bias condition change. However, it is recommended to take this point into account if the MCU is used in tough humidity conditions.
4. $t_{SU(HSE)}$ is the startup time measured from the moment it is enabled (by software) to a stabilized 8 MHz oscillation is reached. This value is measured for a standard crystal resonator and it can vary significantly with the crystal manufacturer.

For C_{L1} and C_{L2}, it is recommended to use high-quality external ceramic capacitors in the 5 pF to 25 pF range (typ.), designed for high-frequency applications, and selected to match the requirements of the crystal or resonator (see *Figure 17*). C_{L1} and C_{L2} are usually the same size. The crystal manufacturer typically specifies a load capacitance which is the series combination of C_{L1} and C_{L2}. PCB and MCU pin capacitance must be included (10 pF can be used as a rough estimate of the combined pin and board capacitance) when sizing C_{L1} and C_{L2}. Refer to the application note AN2867 “Oscillator design guide for ST microcontrollers” available from the ST website *www.st.com*.

Table 32. MSI oscillator characteristics (continued)

Symbol	Parameter	Condition	Typ	Max	Unit
$t_{STAB(MSI)}$[2]	MSI oscillator stabilization time	MSI range 0	-	40	µs
		MSI range 1	-	20	
		MSI range 2	-	10	
		MSI range 3	-	4	
		MSI range 4	-	2.5	
		MSI range 5	-	2	
		MSI range 6, Voltage range 1 and 2	-	2	
		MSI range 3, Voltage Range 3	-	3	
$f_{OVER(MSI)}$	MSI oscillator frequency overshoot	Any range to range 5	-	4	MHz
		Any range to range 6	-	6	

1. This is a deviation for an individual part, once the initial frequency has been measured.
2. Guaranteed by characterization results.

6.3.8 PLL characteristics

The parameters given in *Table 33* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 13*.

Table 33. PLL characteristics

Symbol	Parameter	Value			Unit
		Min	Typ	Max[1]	
f_{PLL_IN}	PLL input clock[2]	2	-	24	MHz
	PLL input clock duty cycle	45	-	55	%
f_{PLL_OUT}	PLL output clock	2	-	32	MHz
t_{LOCK}	Worst case PLL lock time PLL input = 2 MHz PLL VCO = 96 MHz	-	100	130	µs
Jitter	Cycle-to-cycle jitter	-	-	± 600	ps
$I_{DDA}(PLL)$	Current consumption on V_{DDA}	-	220	450	µA
$I_{DD}(PLL)$	Current consumption on V_{DD}	-	120	150	

1. Guaranteed by characterization results.
2. Take care of using the appropriate multiplier factors so as to have PLL input clock values compatible with the range defined by f_{PLL_OUT}.

Input/output AC characteristics

The definition and values of input/output AC characteristics are given in *Figure 19* and *Table 44*, respectively.

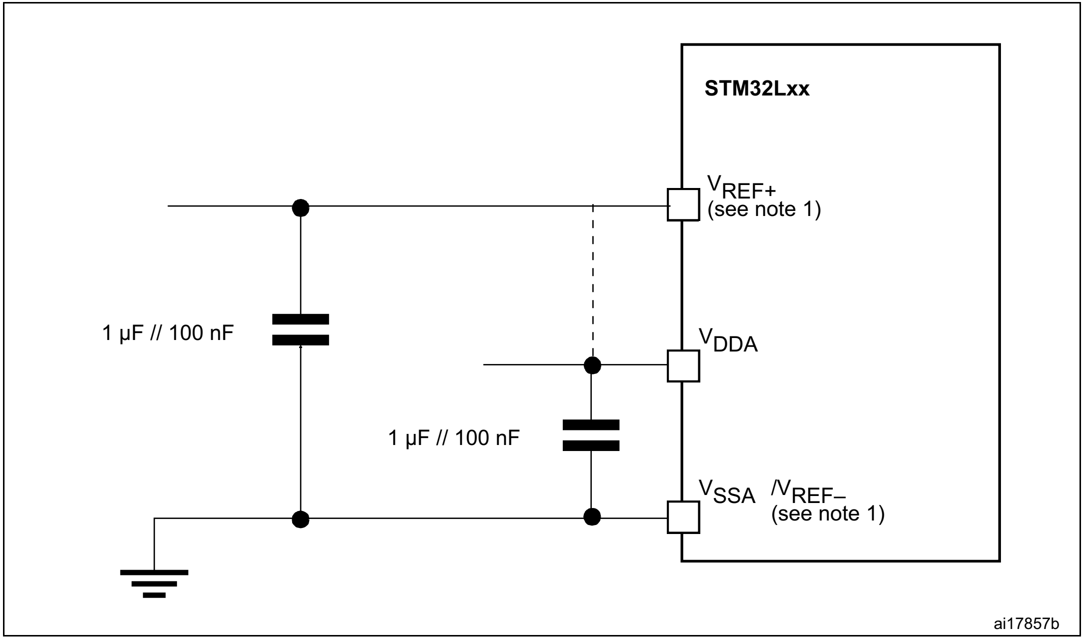
Unless otherwise specified, the parameters given in *Table 44* are derived from tests performed under ambient temperature and V_{DD} supply voltage conditions summarized in *Table 13*.

Table 44. I/O AC characteristics(1)

OSPEEDRx [1:0] bit value(1)	Symbol	Parameter	Conditions	Min	Max(2)	Unit
00	$f_{max(IO)out}$	Maximum frequency(3)	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	400	kHz
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	400	
	$t_{f(IO)out}$ $t_{r(IO)out}$	Output rise and fall time	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	625	ns
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	625	
01	$f_{max(IO)out}$	Maximum frequency(3)	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	2	MHz
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	1	
	$t_{f(IO)out}$ $t_{r(IO)out}$	Output rise and fall time	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	125	ns
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	250	
10	$F_{max(IO)out}$	Maximum frequency(3)	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	10	MHz
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	2	
	$t_{f(IO)out}$ $t_{r(IO)out}$	Output rise and fall time	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	25	ns
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	125	
11	$F_{max(IO)out}$	Maximum frequency(3)	C_L = 50 pF, V_{DD} = 2.7 V to 3.6 V	-	50	MHz
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	8	
	$t_{f(IO)out}$ $t_{r(IO)out}$	Output rise and fall time	C_L = 30 pF, V_{DD} = 2.7 V to 3.6 V	-	5	ns
			C_L = 50 pF, V_{DD} = 1.65 V to 2.7 V	-	30	
-	t_{EXTIpw}	Pulse width of external signals detected by the EXTI controller	-	8	-	

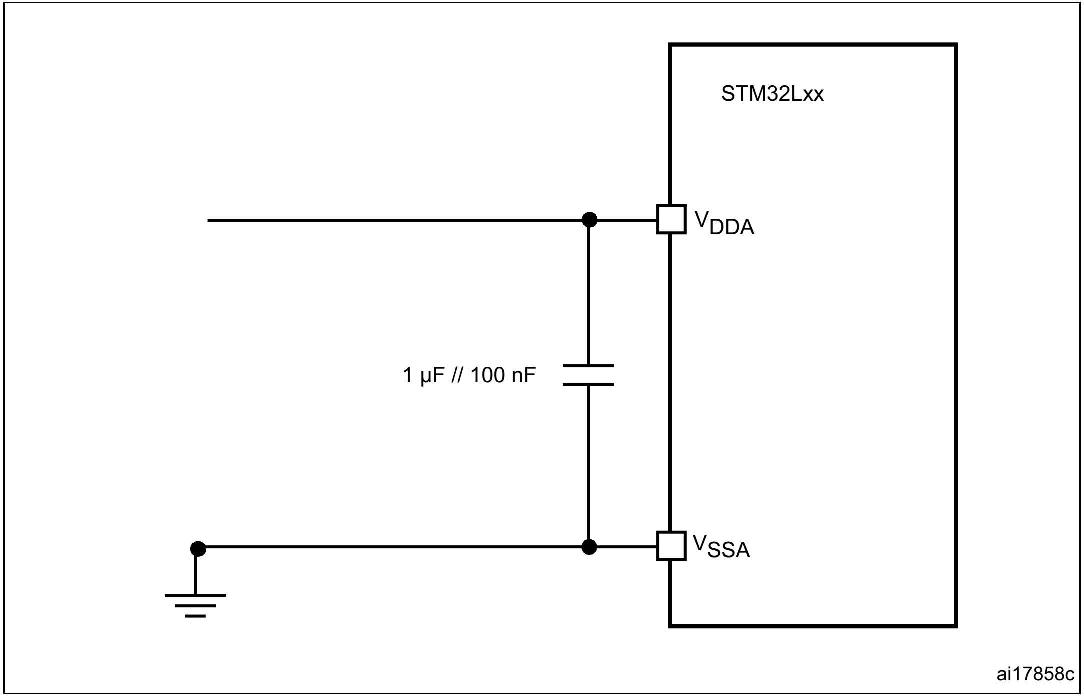
1. The I/O speed is configured using the OSPEEDRx[1:0] bits. Refer to the STM32L151x6/8/B and STM32L152x6/8/B reference manual for a description of GPIO Port configuration register.
2. Guaranteed by design.
3. The maximum frequency is defined in *Figure 19*.

Figure 29. Power supply and reference decoupling (V_{REF+} not connected to V_{DDA})



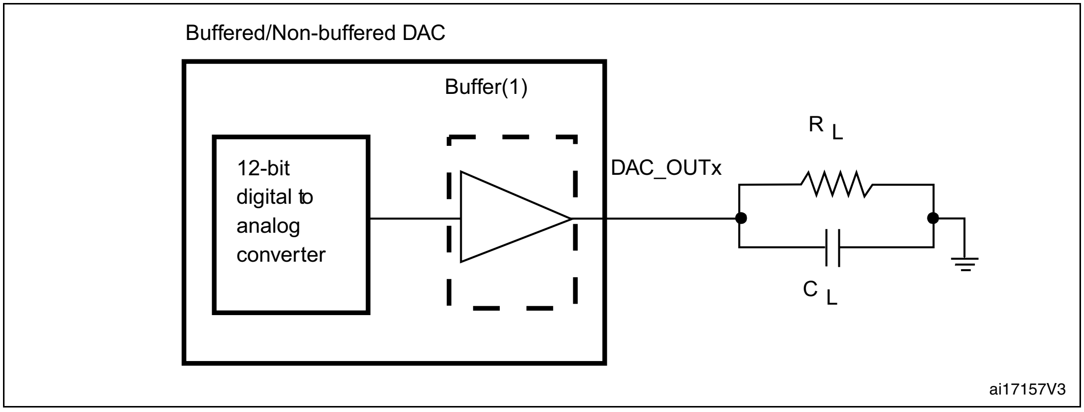
1. V_{REF+} and V_{REF-} inputs are available only on 100-pin packages.

Figure 30. Power supply and reference decoupling (V_{REF+} connected to V_{DDA})



1. V_{REF+} and V_{REF-} inputs are available only on 100-pin packages.

Figure 31. 12-bit buffered /non-buffered DAC



1. The DAC integrates an output buffer that can be used to reduce the output impedance and to drive external loads directly without the use of an external operational amplifier. The buffer can be bypassed by configuring the BOFFx bit in the DAC_CR register.

6.3.19 Temperature sensor characteristics

Table 58. Temperature sensor calibration values

Calibration value name	Description	Memory address
TS_CAL1	TS ADC raw data acquired at temperature of 30 °C, V_{DDA}= 3 V	0x1FF8 007A-0x1FF8 007B
TS_CAL2	TS ADC raw data acquired at temperature of 110 °C V_{DDA}= 3 V	0x1FF8 007E-0x1FF8 007F

Table 59. Temperature sensor characteristics

Symbol	Parameter	Min	Typ	Max	Unit
T_L(1)	V_{SENSE} linearity with temperature	-	±1	±2	°C
Avg_Slope(1)	Average slope	1.48	1.61	1.75	mV/°C
V_{110}	Voltage at 110°C ±5°C(2)	612	626.8	641.5	mV
$I_{DDA(TEMP)}$(3)	Current consumption	-	3.4	6	µA
t_{START}(3)	Startup time	-	-	10	µs
T_{S_temp}(4)(3)	ADC sampling time when reading the temperature	10	-	-	

1. Guaranteed by characterization results.
2. Measured at V_{DD} = 3 V ±10 mV. V110 ADC conversion result is stored in the TS_CAL2 byte.
3. Guaranteed by design.
4. Shortest sampling time can be determined in the application by multiple iterations.

6.3.21 LCD controller (STM32L152xx only)

The STM32L152xx embeds a built-in step-up converter to provide a constant LCD reference voltage independently from the V_{DD} voltage. An external capacitor C_{ext} must be connected to the V_{LCD} pin to decouple this converter.

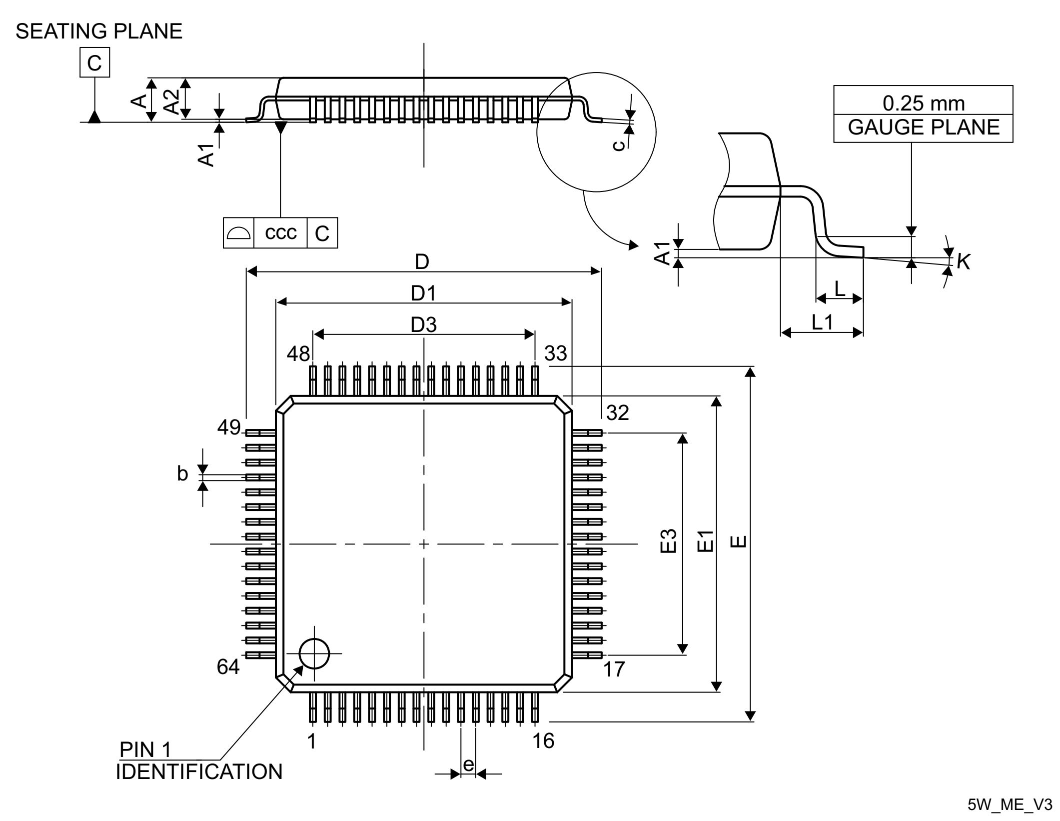
Table 62. LCD controller characteristics

Symbol	Parameter	Min	Typ	Max	Unit
V_{LCD}	LCD external voltage	-	-	3.6	V
V_{LCD0}	LCD internal reference voltage 0	-	2.6	-	
V_{LCD1}	LCD internal reference voltage 1	-	2.73	-	
V_{LCD2}	LCD internal reference voltage 2	-	2.86	-	
V_{LCD3}	LCD internal reference voltage 3	-	2.98	-	
V_{LCD4}	LCD internal reference voltage 4	-	3.12	-	
V_{LCD5}	LCD internal reference voltage 5	-	3.26	-	
V_{LCD6}	LCD internal reference voltage 6	-	3.4	-	
V_{LCD7}	LCD internal reference voltage 7	-	3.55	-	
C_{ext}	V_{LCD} external capacitance	0.1	-	2	µF
I_{LCD}(1)	Supply current at V_{DD} = 2.2 V	-	3.3	-	µA
	Supply current at V_{DD} = 3.0 V	-	3.1	-	
R_{Htot}(2)	Low drive resistive network overall value	5.28	6.6	7.92	MΩ
R_L(2)	High drive resistive network total value	192	240	288	kΩ
V_{44}	Segment/Common highest level voltage	-	-	V_{LCD}	V
V_{34}	Segment/Common 3/4 level voltage	-	3/4 V_{LCD}	-	V
V_{23}	Segment/Common 2/3 level voltage	-	2/3 V_{LCD}	-	
V_{12}	Segment/Common 1/2 level voltage	-	1/2 V_{LCD}	-	
V_{13}	Segment/Common 1/3 level voltage	-	1/3 V_{LCD}	-	
V_{14}	Segment/Common 1/4 level voltage	-	1/4 V_{LCD}	-	
V_0	Segment/Common lowest level voltage	0	-	-	
ΔVxx(3)	Segment/Common level voltage error T_A = -40 to 85 °C	-	-	±50	mV

1. LCD enabled with 3 V internal step-up active, 1/8 duty, 1/4 bias, division ratio= 64, all pixels active, no LCD connected
2. Guaranteed by design.
3. Guaranteed by characterization results.

7.2 LQFP64 10 x 10 mm, 64-pin low-profile quad flat package information

Figure 35. LQFP64 10 x 10 mm, 64-pin low-profile quad flat package outline



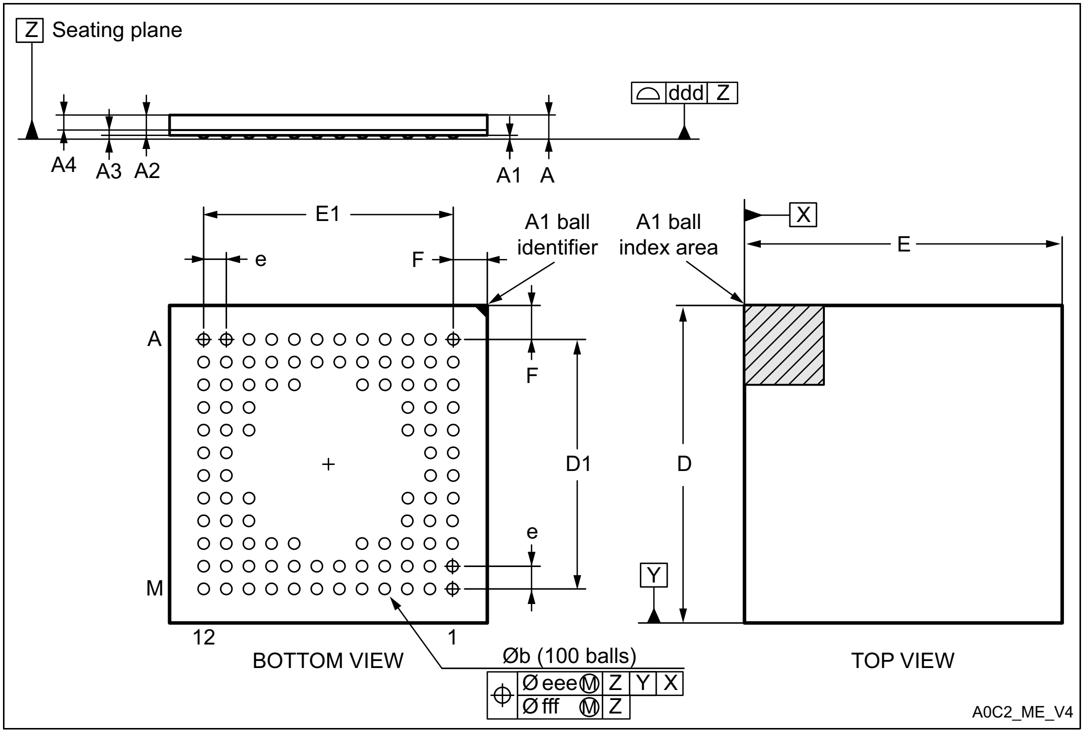
1. Drawing is not to scale.

Table 64. LQFP64 10 x 10 mm, 64-pin low-profile quad flat package mechanical data

Symbol	millimeters			inches(1)		
	Min	Typ	Max	Typ	Min	Max
A	-	-	1.600	-	-	0.0630
A1	0.050	-	0.150	0.0020	-	0.0059
A2	1.350	1.400	1.450	0.0531	0.0551	0.0571
b	0.170	0.220	0.270	0.0067	0.0087	0.0106
c	0.090	-	0.200	0.0035	-	0.0079
D	-	12.000	-	-	0.4724	-
D1	-	10.000	-	-	0.3937	-
D3	-	7.500	-	-	0.2953	-
E	-	12.000	-	-	0.4724	-
E1	-	10.000	-	-	0.3937	-

7.5 UFBGA100 7 x 7 mm, 0.5 mm pitch, ultra thin fine-pitch ball grid array package information

Figure 44. UFBGA100, 7 x 7 mm, 0.5 mm pitch, package outline



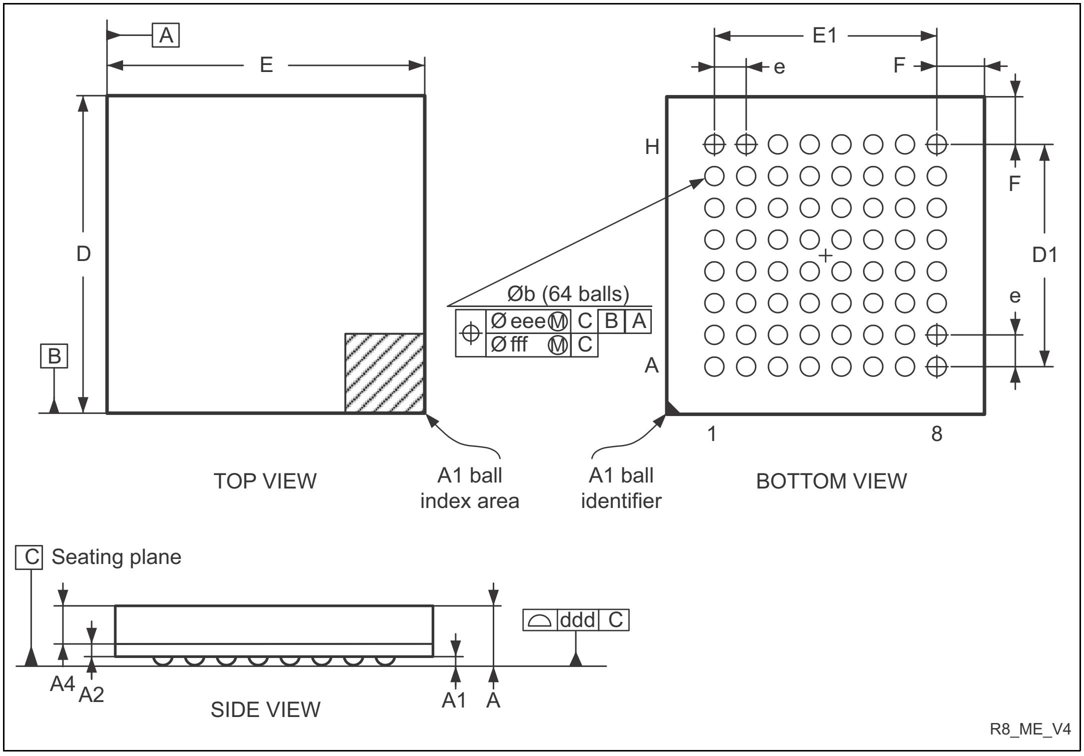
1. Drawing is not to scale.

Table 67. UFBGA100 7 x 7 mm, 0.5 mm pitch, package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	0.6	-	-	0.0236
A1	0.05	0.08	0.11	0.002	0.0031	0.0043
A2	0.4	0.45	0.5	0.0157	0.0177	0.0197
A3	0.08	0.13	0.18	0.0031	0.0051	0.0071
A4	0.27	0.32	0.37	0.0106	0.0126	0.0146
b	0.2	0.25	0.3	0.0079	0.0098	0.0118
D	6.95	7	7.05	0.2736	0.2756	0.2776
D1	5.45	5.5	5.55	0.2146	0.2165	0.2185
E	6.95	7	7.05	0.2736	0.2756	0.2776
E1	5.45	5.5	5.55	0.2146	0.2165	0.2185
e	-	0.5	-	-	0.0197	-
F	0.7	0.75	0.8	0.0276	0.0295	0.0315
ddd	-	-	0.1	-	-	0.0039

7.6 TFBGA64 5 x 5 mm, 0.5 mm pitch, thin fine-pitch ball grid array package information

Figure 47. TFBGA64 5 x 5 mm, 0.5 mm pitch, package outline



1. Drawing is not to scale.

Table 69. TFBGA64 5 x 5 mm, 0.5 mm pitch, package mechanical data

Symbol	millimeters			inches[1]		
	Min	Typ	Max	Min	Typ	Max
A	-	-	1.200	-	-	0.0472
A1	0.150	-	-	0.0059	-	-
A2	-	0.200	-	-	0.0079	-
A4	-	-	0.600	-	-	0.0236
b	0.250	0.300	0.350	0.0098	0.0118	0.0138
D	4.850	5.000	5.150	0.1909	0.1969	0.2028
D1	-	3.500	-	-	0.1378	-
E	4.850	5.000	5.150	0.1909	0.1969	0.2028
E1	-	3.500	-	-	0.1378	-
e	-	0.500	-	-	0.0197	-
F	-	0.750	-	-	0.0295	-
ddd	-	-	0.080	-	-	0.0031

Table 73. Document revision history (continued)

Date	Revision	Changes
17-June-2011	5	Modified 1st page (low power features) Added STM32L15xC6 and STM32L15xR6 devices (32 Kbytes of Flash memory). Modified *Section 3.6: GPIOs (general-purpose inputs/outputs) on page 22* Modified *Section 6.3: Operating conditions on page 53* Modified *Table 55: ADC accuracy on page 95*, *Table 57: DAC characteristics on page 99* and *Table 60: Comparator 1 characteristics on page 102*
25-Jan-2012	6	*Features*: updated internal multispeed low power RC. *Table 2: Ultralow power STM32L15xx6/8/B device features and peripheral counts*: LCD 4x44 and 8x40 available for both 64- and 128-Kbyte devices; two comparators available for all devices. *Table 3: Functionalities depending on the operating power supply range*: added footnote *1*. *Figure 8: STM32L15xCx UFQFPN48 pinout*: replaced VFQPN48 by UFQFPN48 as name of package. *Table 8: STM32L15xx6/8/B pin definitions*: replaced PH0/PH1 by PC14/PC15. *Table 9: Alternate function input/output*: removed EVENT OUT from PH2 port, AFIO15 column. *Table 19: Current consumption in Sleep mode*: updated MSI conditions and f_{HCLK}. *Table 20: Current consumption in Low power run mode*: updated some temperature conditions; added footnote *2.* *Table 21: Current consumption in Low power sleep mode*: updated some temperature conditions and one of the MSI clock conditions. *Table 22: Typical and maximum current consumptions in Stop mode*: updated I_{DD} (WU from Stop) parameter. *Table 23: Typical and maximum current consumptions in Standby mode*: updated I_{DD} (WU from Standby) parameter. *Table 25: Low-power mode wakeup timings*: updated f_{HCLK} value for $t_{WUSLEEP\_LP}$; updated typical value of parameter “Wakeup from Stop mode, regulator in Run mode”. *Table 24: Peripheral current consumption*: replaced GPIOF by GPIOH. *Table 33: PLL characteristics*: updated “PLL output clock” *Table 35: Flash memory and data EEPROM characteristics*: updated all information for I_{DD}. *Figure 19: I/O AC characteristics definition*: replaced the falling edge “$t_{r(IO)out}$” by “$t_{f(IO)out}$”. *Table 47: I2C characteristics*: amended footnote *2.* *Table 54: ADC characteristics*: updated f_S max value for direct channels, 6-bit sampling rate. *Table 55: ADC accuracy*: Updated the first, third and fourth f_{ADC} test condition. *Table 59: Temperature sensor characteristics*: updated typ, min, and max values of the T_{S_temp} parameter.